RELIABILITY MONITOR

DS1100Z-25 JAN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0243	DM242094AJC	8	SOIC	150x1.4	Carsem

PROCESS D6W-1P2M,HPVt,E2,TCZ PBL:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
30770	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS		80	500	HRS	0
		125C, 6.0 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
30767	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
30768	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
30769	PRECONDITION U/S	J-STD-020		4	1	DYS	0
		TOTAL:					0
30771	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
30772	BIASED MOISTURE	85/85, 5.5 VOLTS		77	500	HRS	0
				77	1000	HRS	0
		TOTAL:					0

PROJECT NO: 25544

RELIABILITY MONITOR

DS1100Z-25 JAN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0243	DM242094AJC	8	SOIC	150x1.4	Carsem

PROCESS D6W-1P2M,HPVt,E2,TCZ PBL:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30773	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
		TOTAL:				0

PROJECT NO: 25544

RELIABILITY MONITOR

DS1100Z-25 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0312	DK242100AHC	8	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS D6W-1P2M,HPVt,E2,TCZ PBL:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31254	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31251	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
31252	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31253	PRECONDITION U/S	J-STD-020		4	1	DYS	0
		TOTAL:					0
31255	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
31256	BIASED MOISTURE	85/85, 5.5 VOLTS		77	500	HRS	0
				77	1000	HRS	0
		TOTAL:					0

PROJECT NO: 26479

RELIABILITY MONITOR

DS1100Z-25 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0312	DK242100AHC	8	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS D6W-1P2M,HPVt,E2,TCZ PBL:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31257	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	39	168	HRS	0
		TOTAL:				0

PROJECT NO: 26479

RELIABILITY MONITOR

DS1100Z-25 JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0323	DJ330003ACC	8	SOIC	150x1.4	NSEB

PROCESS D6W-1P2M,HPVt,E2,TCZ PBL:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31899	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31896	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
31897	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31898	PRECONDITION U/S	J-STD-020		4	1	DYS	0
		TOTAL:					0
31900	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	
		TOTAL:					0
31901	BIASED MOISTURE	85/85, 5.5 VOLTS		77	500	HRS	0
				77	1000	HRS	
		TOTAL:					0

PROJECT NO: 27782

RELIABILITY MONITOR

DS1100Z-25 JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1100	A3	0323	DJ330003ACC	8	SOIC	150x1.4	NSEB

PROCESS D6W-1P2M,HPVt,E2,TCZ PBL:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31902	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
		TOTAL:				0

PROJECT NO: 27782

RELIABILITY MONITOR

DS1232L JUL '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0111	DE049638ADB	8	SOIC	150x1.4	OSEP

PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
30185	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS		79	500	HRS	0
		125C, 7.0 VOLTS		79	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.45E+07		0
30182	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
30183	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
30184	PRECONDITION U/S	J-STD-020		4	7	DYS	0
		TOTAL:					0
30186	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
30187	HAST	130C, 85%R.H.,5.5V		77	96	HRS	0
		TOTAL:					0
30188	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		40	168	HRS	0

PROJECT NO: 24602

RELIABILITY MONITOR

DS1232L JUL '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0111	DE049638ADB	8	SOIC	150x1.4	OSEP

PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60%
Ea: 0.7
β: 0

Tuse: 25 °C
Vuse: 5.5 Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0

PROJECT NO: 24602

RELIABILITY MONITOR

DS1232L JAN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0252	DK235629ABA	8	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
30758	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS		80	500	HRS	0
		125C, 7.0 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
30755	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
30756	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
30757	PRECONDITION U/S	J-STD-020		4	7	DYS	0
		TOTAL:					0
30759	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
30760	HAST	130C, 85%R.H.,5.5V		77	96	HRS	0

PROJECT NO: 25545

RELIABILITY MONITOR

DS1232L JAN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0252	DK235629ABA	8	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
PB_RESIST	(#1) FA did not find any anomalies, 9/11/03.	30014717	
LEVELS	(#2) FA did not find any anomalies, 9/11/03.	30014719	

30761	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
		TOTAL:				0

PROJECT NO: 25545

RELIABILITY MONITOR

DS1232L APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0310	DM304031AHB	8	SOIC	150x1.4	Carsem

PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31302	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31299	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
31300	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31301	PRECONDITION U/S	J-STD-020		4	7	DYS	0
		TOTAL:					0
31303	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
31304	HAST	130C, 85%R.H.,5.5V		77	96	HRS	0
		TOTAL:					0
31305	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		40	168	HRS	0

PROJECT NO: 26499

RELIABILITY MONITOR

DS1232L APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0310	DM304031AHB	8	SOIC	150x1.4	Carsem

PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60%
Ea: 0.7
β: 0

Tuse: 25 °C
Vuse: 5.5 Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0

PROJECT NO: 26499

RELIABILITY MONITOR

DS1232L JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1232	C2-L	0327	DK343027AAB	8	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS 1P, 1M, 0.8um, PdplDiode, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31906	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31903	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
31904	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31905	PRECONDITION U/S	J-STD-020		4	7	DYS	0
		TOTAL:					0
31907	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
31909	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		40	168	HRS	0
		TOTAL:					0

PROJECT NO: 27781

RELIABILITY MONITOR

DS1233Z-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1233	A5-500	0311	DU321432DC	3	SOT223	140x1.7	Hana

PROCESS 1P, 1M, 1.2um, ZTC P1, Ndepletion ,L Passivation w/Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31309	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		79	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.50E+07		0
31306	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
31307	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31308	PRECONDITION U/S	J-STD-020		4	2	DYS	0
		TOTAL:					0
31310	TEMP CYCLE	-55C TO 125C		40	500	CYS	
				40	1000	CYS	0
		TOTAL:					0
31311	HAST	130C, 85%R.H.,5.5V		77	96	HRS	0
		TOTAL:					0
31312	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		40	168	HRS	0

PROJECT NO: 21798

RELIABILITY MONITOR

DS1233Z-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1233	A5-500	0311	DU321432DC	3	SOT223	140x1.7	Hana

PROCESS 1P, 1M, 1.2um, ZTC P1, Ndepletion ,L Passivation w/Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60%
Ea: 0.7
β: 0

Tuse: 25 °C
Vuse: 5.5 Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0

PROJECT NO: 21798

RELIABILITY MONITOR

DS1233Z-010 JUL '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1233	A5-500	0326	DU338107AKA	3	SOT223	140x1.7	Hana

PROCESS 1P, 1M, 1.2um, ZTC P1, Ndepletion ,L Passivation w/Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31913	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31910	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
31911	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31912	PRECONDITION U/S	J-STD-020		4	2	DYS	0
		TOTAL:					0
31914	TEMP CYCLE	-55C TO 125C		40	700	CYS	0
				40	1000	CYS	0
		TOTAL:					0
31915	HAST	130C, 85%R.H.,5.5V		77	96	HRS	0
		TOTAL:					0
31916	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		40	168	HRS	0

PROJECT NO: 26501

RELIABILITY MONITOR

DS1267-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1267	A1-50	0309	DK236020AFA	20	TSSOP	4.4x0.9	ATP (Amkor, PI)

PROCESS 1P, 1M, 1.2um, II Poly1 , TEOS Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31316	HIGH TEMP OP LIFE	125C, 5.5 V, -4.0V		80	500	HRS	0
		125C, 5.5 V, -4.0V		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31313	ULTRASOUND	J-STD-020		4	5	DYS	0
		TOTAL:					0
31314	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31315	PRECONDITION U/S	J-STD-020		4	2	DYS	0
		TOTAL:					0
31317	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
31318	BIASED MOISTURE	85/85, 5.5 VOLTS		77	500	HRS	0
				77	1000	HRS	0
		TOTAL:					0

PROJECT NO: 18887

RELIABILITY MONITOR

DS1267-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1267	A1-50	0309	DK236020AFA	20	TSSOP	4.4x0.9	ATP (Amkor, PI)

PROCESS 1P, 1M, 1.2um, II Poly1 , TEOS Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31319	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
		TOTAL:				0

PROJECT NO: 18887

RELIABILITY MONITOR

DS1302 JUN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1302	A4	0321	DE117012AA	8	PDIP	300	OSEP

PROCESS 1P, 2M, 0.8um, ESD Pdepletion,HP Vts, Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31640	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31641	TEMP CYCLE	-55C TO 125C		45	500	CYS	0
				45	1000	CYS	0
		TOTAL:					0
31642	BIASED MOISTURE	85/85, 5.5 VOLTS		77	500	HRS	0
				77	1000	HRS	0
		TOTAL:					0
31643	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		45	168	HRS	0
		TOTAL:					0

PROJECT NO: 27260

RELIABILITY MONITOR

DS1620 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1620	D1	0310	DJ232810AAB	8	SOIC	150x1.4	NSEB

PROCESS D8W-1P1M,HPVt,E2 LOCOS:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31323	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31321	STORAGE LIFE	125C		244	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		244	168	HRS	
	CONVECTION REFLOW	235C		244	3	PASS	0
		TOTAL:					0
31322	PRECONDITION U/S	J-STD-020		4	7	DYS	0
		TOTAL:					0
31324	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
31325	BIASED MOISTURE	85/85, 5.5 VOLTS		70	500	HRS	0
				70	1000	HRS	0
		TOTAL:					0
31326	WRITE CYCLE STRESS	85 C, 5.5 VOLTS		50	50	KCYS	0
		TOTAL:					0

PROJECT NO: 26500

RELIABILITY MONITOR

DS1620 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1620	D1	0310	DJ232810AAB	8	SOIC	150x1.4	NSEB

PROCESS D8W-1P1M,HPVt,E2 LOCOS:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31327	STORAGE LIFE	150C	50	500	HRS	0
			50	1000	HRS	0
		TOTAL:				0

PROJECT NO: 26500

RELIABILITY MONITOR

DS1621 MAR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0237	DE106688AAB	8	SOIC	150x1.4	OSEP

PROCESS D8W-1P1M,HPVt,E2 LOCOS:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
30966	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS		75	500	HRS	0
		125C, 7.0 VOLTS		75	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	13	DEVICE HRS: 7.07E+07		0
30963	ULTRASOUND	J-STD-020		4	7	DYS	0
		TOTAL:					0
30964	STORAGE LIFE	125C		240	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		240	168	HRS	
	CONVECTION REFLOW	235C		240	3	PASS	0
		TOTAL:					0
30965	PRECONDITION U/S	J-STD-020		4	7	DYS	0
		TOTAL:					0
30967	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
30968	BIASED MOISTURE	85/85, 5.5 VOLTS		70	500	HRS	0
				70	1000	HRS	0
		TOTAL:					0

PROJECT NO: 25960

RELIABILITY MONITOR

DS1621 MAR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0237	DE106688AAB	8	SOIC	150x1.4	OSEP

PROCESS D8W-1P1M,HPVt,E2 LOCOS:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
30969	WRITE CYCLE STRESS	85 C, 7.0 VOLTS	50	50	KCYS	0
		TOTAL:				0
30970	STORAGE LIFE	150C	50	500	HRS	0
			50	1000	HRS	0
		TOTAL:				0

PROJECT NO: 25960

RELIABILITY MONITOR

DS1621 JUN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0247	DK104614AAB	8	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS D8W-1P1M,HPVt,E2 LOCOS:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31729	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		77	500	HRS	0
		125C, 5.5 VOLTS		77	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	13	DEVICE HRS: 7.26E+07		0
31726	ULTRASOUND	J-STD-020		4	7	DYS	0
		TOTAL:					0
31727	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31728	PRECONDITION U/S	J-STD-020		4	7	DYS	0
		TOTAL:					0
31730	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0
		TOTAL:					0
31731	BIASED MOISTURE	85/85, 5.5 VOLTS		70	500	HRS	0
				70	1000	HRS	0
		TOTAL:					0

PROJECT NO: 27259

RELIABILITY MONITOR

DS1621 JUN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1621	A7	0247	DK104614AAB	8	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS D8W-1P1M,HPVt,E2 LOCOS:GOI Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31732	WRITE CYCLE STRESS	85 C, 5.5 VOLTS	50	50	KCYS	0
		TOTAL:				0
31733	STORAGE LIFE	150C	50	500	HRS	0
			50	1000	HRS	0
		TOTAL:				0

PROJECT NO: 27259

RELIABILITY MONITOR

DS1803-010 OCT '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0234	DK236047AAB	16	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS 1P, 2M, 0.8um, PdplDiode , WJ Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
30229	HIGH VOLTAGE LIFE	125C, 7.0 VOLTS		80	500	HRS	0
		125C, 7.0 VOLTS		80	500	HRS	0
		125C, 7.0 VOLTS		80	500	HRS	0
		125C, 7.0 VOLTS		80	1000	HRS	0
		125C, 7.0 VOLTS		80	1000	HRS	0
		125C, 7.0 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	4	DEVICE HRS: 2.26E+08		0
30226	ULTRASOUND	J-STD-020		4	2	DYS	0
		TOTAL:					0
30227	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
30228	PRECONDITION U/S	J-STD-020		4	2	DYS	0
		TOTAL:					0
30230	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0

PROJECT NO: 24620

RELIABILITY MONITOR

DS1803-010 OCT '02 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0234	DK236047AAB	16	SOIC	150x1.4	ATP (Amkor, PI)

PROCESS 1P, 2M, 0.8um, PdplDiode , WJ Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0
30231	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	
		TOTAL:				0
30232	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
		TOTAL:				0

PROJECT NO: 24620

RELIABILITY MONITOR

DS1803-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0304	DE322628AAB	16	SOIC	150x1.4	OSEP

PROCESS 1P, 2M, 0.8um, PdplDiode , WJ Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31261	HIGH TEMP OP LIFE	125C, 5.25 VOLTS		80	500	HRS	0
		125C, 5.25 VOLTS		80	500	HRS	0
		125C, 5.25 VOLTS		80	500	HRS	0
		125C, 5.25 VOLTS		80	1000	HRS	0
		125C, 5.25 VOLTS		80	1000	HRS	0
		125C, 5.25 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	4	DEVICE HRS: 2.26E+08		0
31258	ULTRASOUND	J-STD-020		4	2	DYS	0
		TOTAL:					0
31259	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	85 C/85% R.H.		241	168	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
31260	PRECONDITION U/S	J-STD-020		4	2	DYS	0
		TOTAL:					0
31262	TEMP CYCLE	-55C TO 125C		40	500	CYS	0
				40	1000	CYS	0

PROJECT NO: 26480

RELIABILITY MONITOR

DS1803-010 APR '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS1803	A2	0304	DE322628AAB	16	SOIC	150x1.4	OSEP

PROCESS 1P, 2M, 0.8um, PdplDiode , WJ Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0
31263	BIASED MOISTURE	85/85, 5.5 VOLTS	77	500	HRS	0
			77	1000	HRS	0
		TOTAL:				0
31264	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED	40	168	HRS	0
		TOTAL:				0

PROJECT NO: 26480

RELIABILITY MONITOR

DS2118M JUN '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2118M	C1-6"	0303	DM316629ABA	36	SSOP	7.5x2.4	Carsem
PROCESS	D6S-1P1M,HPVt,N+ESD,TCN3		ALOCO		Laser/Nit - Pass/Nit - General LaserPrb		

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31737	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		80	500	HRS	0
		125C, 5.5 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31734	ULTRASOUND	J-STD-020		4	6	DYS	0
		TOTAL:					0
31735	STORAGE LIFE	125C		238	48	HRS	
	MOISTURE SOAK	85 C/85% R.H.		238	168	HRS	
	CONVECTION REFLOW	235C		238	3	PASS	0
		TOTAL:					0
31736	PRECONDITION U/S	J-STD-020		4	6	DYS	0
		TOTAL:					0
31738	TEMP CYCLE	-55C TO 125C		77	500	CYS	0
				77	1000	CYS	0
		TOTAL:					0
31739	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		77	168	HRS	0
		TOTAL:					0

PROJECT NO: 27359

RELIABILITY MONITOR

DS21352 FEB '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21352	A4	0242	DK036653AAA	100	LQFP	14x14x	ATP (Amkor, PI)

PROCESS 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GO Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31029	HIGH TEMP OP LIFE	125C, 3.3 VOLTS		77	500	HRS	0
		125C, 3.3 VOLTS		63	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	14	DEVICE HRS: 6.60E+07		0

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
SHORT	(#5,6)		
RCV_MM	(#1,3,7,8,11,12)		
OPEN	(#9,10)		
LB0O	(#2,4)		

31026	ULTRASOUND	J-STD-020		4	2	DYS	0
		TOTAL:					0
31027	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	30C/60% R.H.		241	192	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
JIT_TOL	(#1)		
IBO4_3V	(#2)		

31028	PRECONDITION U/S	J-STD-020		4	5	DYS	0

PROJECT NO: 26120

RELIABILITY MONITOR

DS21352 FEB '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21352	A4	0242	DK036653AAA	100	LQFP	14x14x	ATP (Amkor, PI)

PROCESS 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GO Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				0
FAILURE MODE		**VERIFICATION**	**FA NUMBER**	**FAILURE MECHANISM**		
CRACK		THERE IS A 100% INCREASE OF DELAMINATION IN THE DIE ATTACH AREA OF ALL PKGS.				
31030	TEMP CYCLE	-55C TO 125C	80	500	CYS	0
			69	1000	CYS	0
		TOTAL:				0
FAILURE MODE		**VERIFICATION**	**FA NUMBER**	**FAILURE MECHANISM**		
RCV_MM		(#1-9)				
31031	HAST, NO BIAS	130C, 85% R.H.	78	96	HRS	0
		TOTAL:				0
FAILURE MODE		**VERIFICATION**	**FA NUMBER**	**FAILURE MECHANISM**		
RCV_MM		(#4,5,6,7,8,9)				
OSC		(#1,2,3)				

PROJECT NO: 26120

RELIABILITY MONITOR

DS21352 MAY '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21352	A4	0312	DC043465AAA	100	LQFP	14x14x	Stats

PROCESS 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GO Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31401	HIGH TEMP OP LIFE	125C, 3.3 VOLTS		77	500	HRS	0
		125C, 3.3 VOLTS		70	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	13	DEVICE HRS: 6.93E+07		0

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
XB LUE	(#5)		
RCV_MM	(#2,4)		
RCV_MM	(# 2,3,5,6,7,8,9)		
OSC	(#1,4,10) (These parts returned to stess. PM)		

31398	ULTRASOUND	J-STD-020		4	2	DYS	0
		TOTAL:					0
31399	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	30C/60% R.H.		241	192	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
XRBS	(#2)		
JIT_TOL	(#1,3)		

31400	PRECONDITION U/S	J-STD-020		4	5	DYS	0
		TOTAL:					0

PROJECT NO: 26759

RELIABILITY MONITOR

DS21352 MAY '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21352	A4	0312	DC043465AAA	100	LQFP	14x14x	Stats

PROCESS 2P, 2M, 0.6um, P2Cap, PdD, HP Vts, GO Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31402	TEMP CYCLE	-55C TO 125C	80	500	CYS	0
			73	1000	CYS	0
		TOTAL:				0

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
RCV_MM	(#5-8)		
OSC	(#1-4)(#1 Returned to stress.PM)		

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
31403	HAST, NO BIAS	130C, 85% R.H.	77	96	HRS	0
		TOTAL:				0

FAILURE MODE	VERIFICATION	FA NUMBER	FAILURE MECHANISM
RCV_MM	(#2,3,4,5,8,9,10)		
OSE	(#1,6,7)		

PROJECT NO: 26759

RELIABILITY MONITOR

DS21Q43A FEB '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21Q43	A3-A	0305	DN039537AAA	128	LQFP	14x20x	ATK (Amkor, K)

PROCESS 1P, 1M, 0.6um, Pdepletion, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
30958	HIGH VOLTAGE LIFE	125C, 6.0 VOLTS		77	500	HRS	0
		125C, 6.0 VOLTS		77	1000	HRS	
		TOTAL:	FAIL RATE (Fits):	13	DEVICE HRS: 7.26E+07		0
30955	ULTRASOUND	J-STD-020		4	1	DYS	0
		TOTAL:					0
30956	STORAGE LIFE	125C		241	24	HRS	
	MOISTURE SOAK	30C/60% R.H.		241	192	HRS	
	CONVECTION REFLOW	235C		241	3	PASS	0
		TOTAL:					0
30957	PRECONDITION U/S	J-STD-020		4	1	DYS	0
		TOTAL:					0
30959	TEMP CYCLE	-55C TO 125C		70	500	CYS	0
				70	1000	CYS	
		TOTAL:					0
30960	BIASED MOISTURE	85/85, 5.5 VOLTS		50	500	HRS	
		TOTAL:					
30961	HAST, NO BIAS	130C, 85% R.H.		40	100	HRS	

PROJECT NO: 24641

RELIABILITY MONITOR

DS21Q43A FEB '03 MONITOR, D.P.

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS21Q43	A3-A	0305	DN039537AAA	128	LQFP	14x20x	ATK (Amkor, K)

PROCESS 1P, 1M, 0.6um, Pdepletion, Low Vts , Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60%
Ea: 0.7
β: 0

Tuse: 25 °C
Vuse: 5.5 Volts

JOB NO	DESCRIPT	CONDITION	QUANTITY	READPOINT	UNITS	NO OF FAILS
		TOTAL:				

PROJECT NO: 24641

RELIABILITY MONITOR

DS2401 MAY '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2401	C2	0323	DM330002AA	3	TO92	150	Carsem

PROCESS 1P, 1M, 0.6um, Pd, Ti/TiN M1 , WJ Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
31647	HIGH TEMP OP LIFE	125C, 6.0 VOLTS		80	500	HRS	0
		125C, 6.0 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
31648	TEMP CYCLE	-55C TO 125C		45	500	CYS	0
				45	1000	CYS	0
		TOTAL:					0
31649	HAST	130C, 85%R.H.,5.5V		77	96	HRS	0
		TOTAL:					0
31650	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		45	168	HRS	0
		TOTAL:					0

PROJECT NO: 27319

RELIABILITY MONITOR

DS2401 AUG '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS2401	C2	0331	DU342603AB	3	TO92	150	Hana

PROCESS 1P, 1M, 0.6um, Pd, Ti/TiN M1 , WJ Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
32237	HIGH TEMP OP LIFE	125C, 6.0 VOLTS		80	500	HRS	0
		125C, 6.0 VOLTS		80	1000	HRS	0
		TOTAL:	FAIL RATE (Fits):	12	DEVICE HRS: 7.55E+07		0
32238	TEMP CYCLE	-55C TO 125C		45	500	CYS	0
				45	1000	CYS	0
		TOTAL:					0
32240	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		45	168	HRS	0
		TOTAL:					0

PROJECT NO: 28159

RELIABILITY MONITOR

DS80C320 SEP '03 MONITOR

DEVICE	REVISION	DATE CD	LOT NUMBER	PINS	PACKAGE	WIDTH	ASSEMBLY SITE
DS80C320	C5	0323	DQ338181AAA	40	PDIP	600	ATEC

PROCESS D6RL-1P1M,SILP1,LLVt,N+ESD PBL:G Passivation w/Nov TEOS Oxide-Nitride

Summary Data with Chi-Square Distribution Assumed.
Stress Ambient Temperature and Voltage to
Field Ambient Temperature And Voltage

Cf: 60% Tuse: 25 °C
Ea: 0.7 Vuse: 5.5 Volts
β: 0

JOB NO	DESCRIPT	CONDITION		QUANTITY	READPOINT	UNITS	NO OF FAILS
32413	HIGH TEMP OP LIFE	125C, 5.5 VOLTS		77	500	HRS	0
		125C, 5.5 VOLTS		77	1000	HRS	
		TOTAL:	FAIL RATE (Fits):	13	DEVICE HRS: 7.26E+07		0
32414	TEMP CYCLE	-55C TO 125C		45	500	CYS	0
				45	1000	CYS	0
		TOTAL:					0
32415	BIASED MOISTURE	85/85, 5.5 VOLTS		77	500	HRS	0
				77	1000	HRS	
		TOTAL:					0
32416	AUTOCLAVE	121C, 2 ATM STEAM, UNBIASED		45	96	HRS	
		TOTAL:					

PROJECT NO: 28609